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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Applicant Young-Joon Park, et al. Docket Number: TI-35623

Serial No.: 10/628,198 Art Unit: 2814

Filed: 07/28/03 Examiner: Ginette Peralta

For: A Two Step Semiconductor Manufacturing Process for  
Copper Interconnects

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NAME OF INVENTOR(S):	
Young-Joon Park, et al.	
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